



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20151105001
Wafer Diameter Change for Select Devices in the LBC3S Process at DL-LIN
Change Notification / Sample Request

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20151105001
Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number:	20151105001		PCN Date:	11/12/2015
Title:	Wafer Diameter Change for Select Devices in the LBC3S Process at DL-LIN			
Customer Contact:	PCN Manager	Dept:	Quality Services	
Proposed 1st Ship Date:	02/12/2016	Estimated Sample availability:	Date Provided at Sample request	
Change Type:				
☐ Assembly Site	☐ Assembly Process	☐ Assembly Materials		
☐ Design	☐ Electrical Specification	☐ Mechanical Specification		
☐ Test Site	☐ Packing/Shipping/Labeling	☐ Test Process		
☐ Wafer Bump Site	☐ Wafer Bump Material	☐ Wafer Bump Process		
☐ Wafer Fab Site	☐ Wafer Fab Materials	☒ Wafer Fab Process		
	☐ Part number change			
PCN Details				
Description of Change:				
This change notification is to announce a <u>wafer diameter change only</u> for select devices in the LBC3S process at DL-LIN. This is not a fab site change.				
Current		New		
Site/Process/Wafer Diameter		Site/Process/ Wafer Diameter		
DL-LIN/LBC3S Process/150mm		DL-LIN/LBC3S Process/ 200mm		
The LBC3 process is a mature process which has been successfully running production since 02/2000 at DL-LIN.				
Reason for Change:				
Continuity of supply.				
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):				
None				

Changes to product identification resulting from this PCN:			
Note: This is <u>not a fab site change</u> . The 6" line and 8" line are in the same location.			
Chip Site	Chip site code (20L)	Chip country code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
Sample Product Shipping Label (not actual product label)			

Product Affected:

SN65HVD1176D	TLC2252CPWR	TLC2262CPWG4	TLV2262IDR
SN65HVD1176DG4	TLC2252CPWRG4	TLC2262CPWR	TLV2262IDRG4
SN65HVD1176DR	TLC2252ID	TLC2262CPWRG4	TLV2262IP
SN65HVD1176DRG4	TLC2252IDG4	TLC2262ID	TLV2262IPW
SN65HVD22D	TLC2252IDR	TLC2262IDG4	TLV2262IPWG4
SN65HVD22DG4	TLC2252IDRG4	TLC2262IDR	TLV2262IPWR
SN65HVD22DR	TLC2252IP	TLC2262IDRG4	TLV2262IPWRG4
SN65HVD22DRG4	TLC2254AID	TLC2262IP	TLV2372IDGK
SN65HVD22P	TLC2254AIDG4	TLV2252AID	TLV2372IDGKG4
SN65HVD22PE4	TLC2254AIDR	TLV2252AIDG4	TLV2372IDGKR
SN65HVD234D	TLC2254AIDRG4	TLV2252AIDR	TLV2372IDGKRG4
SN65HVD234DG4	TLC2254AIN	TLV2252AIDRG4	TLV2462CDGK
SN65HVD234DR	TLC2254AIPW	TLV2252AIP	TLV2462CDGKG4
SN65HVD234DRG4	TLC2254AIPWR	TLV2252AIPW	TLV2462CDGKR
SN75HVD1176D	TLC2254AIPWRG4	TLV2252AIPWG4	TLV2462CDGKRG4
SN75HVD1176DG4	TLC2254CD	TLV2252AIPWR	TLV2462IDGK
SN75HVD1176DR	TLC2254CDG4	TLV2252AIPWRG4	TLV2462IDGKG4
SN75HVD1176DRG4	TLC2254CDR	TLV2252ID	TLV2462IDGKR
TLC084AID	TLC2254CDRG4	TLV2252IDG4	TLV2462IDGKRG4
TLC084AIDG4	TLC2254CN	TLV2252IDR	TLV2463CDGS
TLC084AIDR	TLC2254CPW	TLV2252IDRG4	TLV2463CDGSG4
TLC084AIDRG4	TLC2254CPWG4	TLV2252IP	TLV2463CDGSR
TLC084AIN	TLC2254CPWR	TLV2254AID	TLV2463CDGSRG4
TLC084AIPWP	TLC2254CPWRG4	TLV2254AIDG4	TLV2463IDGS
TLC084AIPWPR	TLC2254ID	TLV2254AIDR	TLV2463IDGSG4
TLC084AIPWPRG4	TLC2254IDG4	TLV2254AIDRG4	TLV2463IDGSR
TLC085AID	TLC2254IDR	TLV2254AIN	TLV2463IDGSRG4
TLC085AIDR	TLC2254IDRG4	TLV2254AIPW	TLV272CDGK
TLC085AIN	TLC2254IN	TLV2254AIPWG4	TLV272CDGKG4
TLC085AIPWP	TLC2262AID	TLV2254AIPWR	TLV272CDGKR
TLC2252AID	TLC2262AIDG4	TLV2254AIPWRG4	TLV272CDGKRG4
TLC2252AIDG4	TLC2262AIDR	TLV2254ID	TLV272IDGK
TLC2252AIDR	TLC2262AIDRG4	TLV2254IDG4	TLV272IDGKG4
TLC2252AIDRG4	TLC2262AIP	TLV2254IDR	TLV272IDGKR
TLC2252AIP	TLC2262AIPE4	TLV2254IDRG4	TLV272IDGKRG4
TLC2252AIPE4	TLC2262AIPW	TLV2254IN	UCC27424D
TLC2252AIPW	TLC2262AIPWG4	TLV2262AID	UCC27424DG4
TLC2252AIPWR	TLC2262AIPWR	TLV2262AIDG4	UCC27424DGN
TLC2252AIPWRG4	TLC2262AIPWRG4	TLV2262AIDR	UCC27424DGN4
TLC2252CD	TLC2262CD	TLV2262AIDRG4	UCC27424DGNR
TLC2252CDG4	TLC2262CDG4	TLV2262AIP	UCC27424DGNRG4
TLC2252CDR	TLC2262CDR	TLV2262AIPW	UCC27424DR
TLC2252CDRG4	TLC2262CDRG4	TLV2262AIPWG4	UCC27424DRG4
TLC2252CP	TLC2262CP	TLV2262AIPWR	UCC27424P
TLC2252CPW	TLC2262CPE4	TLV2262ID	UCC27424PE4

TLC2252CPWG4	TLC2262CPW	TLV2262IDG4		
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Qualification Report

Conversion of select devices from 150mm wafers to 200mm wafers in DFAB

Approve Date 05-Nov-2015

Product Attributes

Attributes	Qual Device: SN65HVD1176 D	Qual Device: SN65HVD22 P	Qual Device: SN65HVD234 D	Qual Device: TLC085AIPWP	Qual Device: TLV2252ID	Qual Device: TLV2254IN	Qual Device: TLV2262ID	Qual Device: TLV2372IDG K	Qual Device: TLV2463IDGS	Qual Device: UCC27424D	QBS Process Reference: SN104605PN
Assembly Site	FMX	FMX	FMX	TAI	FMX	FMX	-	HNT	-	FMX	TAI
Package Family	SOIC	PDIP	SOIC	HTSSOP	SOIC	PDIP	SOIC	MSOP	MSOP	SOIC	LQFP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	-
Wafer Fab Supplier	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB
Wafer Process	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S

-QBS: Qual By Similarity

-Qual Devices qualified at LEVEL1-260C: SN65HVD1176D, SN65HVD234D, TLV2372IDGK, TLV2262ID, TLV2252ID, UCC27424D, TLV2463IDGS,

-Qual Devices qualified at Not Classified: SN65HVD22P, TLV2254IN

-Qual Device TLC085AIPWP is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN65HVD1 176D	Qual Device: SN65HVD2 2P	Qual Device: SN65HVD2 34D	Qual Device: TLC085AI PWP	Qual Device: TLV2252ID	Qual Device: TLV2254IN	Qual Device: TLV2262ID	Qual Device: TLV2372 IDGK	Qual Device: TLV2463I DGS	Qual Device: UCC274 24D	QBS Process Reference: SN104605PN
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	-	-	-	-	-	3/231/0
HBM	ESD - HBM	4000 V	1/3/0	-	1/3/0	-	-	-	-	1/3/0	1/3/0	1/3/0	-
HBM	ESD - HBM	5000 V	-	1/3/0	-	-	-	-	-	-	-	-	-
HBM	ESD - HBM (Bus & Ground pins)	10000V	1/3/0	-	-	-	-	-	-	-	-	-	-
HBM	ESD - HBM (Pin 7, 6 and gnd)	16000 V	-	1/3/0	1/3/0	-	-	-	-	-	-	-	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	-
HTOL	Life Test 155C	1000 Hours	-	-	-	-	-	-	-	-	-	-	3/231/0
LU	Latch-up (per JEDEC78)	1/6/0	1/6/0	-	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	-
TS	Thermal Shock, -65/150C	500 Cycles	-	-	-	-	-	-	-	-	-	-	3/231/0
WBP	Bond Pull	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	-	-	1/76/0	3/228/0
WBS	Ball Bond Shear	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	-	-	1/76/0	-

-Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

-The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

-The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

-The following are equivalent Temp Cycle options per JEDEC47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com